

Amendment to the Claims:

Kindly replace the previous claim set with the claim set which appears below, in which Claims 1, 7 and 15 have been cancelled and Claims 8, 9 and 19 have been amended to read as follows:

Claims 1-2. (Cancelled)

3. (Previously Presented) A lead free soldering material consisting essentially of Sn (tin), 2 to 10 wt.% Ag, Bi, 1 to 3 wt.% Sb, 0.5 to 3 wt.% Cu and 0.05 to 0.3 wt.% Ni, wherein the Sb:Bi wt.% ratio is from 1:1.5-3.

Claims 4-7. (Cancelled)

8. (Currently Amended) Soldering material according to Claim 7 3 having a Ni content of 0.05 to 0.2 wt.%.

9. (Currently Amended) Soldering material according to Claim 8 3 wherein the soldering material is SnAg3.3-4.7Cu0.3-1.7Bi2Sb1Ni0.2.

Claims 10-18. (Cancelled)

19. (Currently Amended) A solder joint formed from the lead free soldering material of Claim 8 3.

Claims 20-25. (Cancelled)

26. (Previously Presented) A lead free soldering material consisting essentially of Sn (tin), 2 to 10 wt.% Ag, 1 to 3 wt.% Bi, 1 to 3 wt.% Sb, 0.5 to 3 wt.% Cu and 0.05 to 0.3 wt.% Ni.